



Product / Package Information	
Package	SOT 223
Body Size	
Lead Count	3
Terminal Finish	100Sn

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	Proprietary	3.30 E-02	71.7	717000	28.27	282719
Thermosets	Epoxy Resin	Proprietary	6.90 E-03	15.0	150000	5.91	59146
Thermosets	Phenol Resin	Proprietary	2.30 E-03	5.0	50000	1.97	19715
Thermosets	Antimony Trioxide	1309-64-4	1.38 E-03	3.0	30000	1.18	11829
Others	Additives	Proprietary	1.38 E-03	3.0	30000	1.18	11829
Thermosets	Brominated Epoxy	Proprietary	9.20 E-04	2.0	20000	0.79	7886
Other inorganic materials	Carbon Black	1333-86-4	1.38 E-04	0.3	3000	0.12	1183
Subtotal			4.60 E-02	100.0	1000000	39	394308

Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.41 E-02	99.9	998998	54.95	549521
Copper & its alloys	Tin	7440-31-5	6.43 E-05	0.1	1002	0.06	551
Subtotal			6.42 E-02	100.0	1000000	55	550072

Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.29 E-04	100	1000000	0.11	1102

External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.59 E-03	100	1000000	1.36	13629

Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.19	1886

Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.80 E-03	100	1000000	2.40	24001

Die Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	14808-60-7	8.73 E-04	49.90	499000	0.75	7485
Organic materials	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	3.50 E-04	20.00	200000	0.30	3000
Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	3.50 E-04	20.00	200000	0.30	3000
Others	Aromatic Amine	Proprietary	8.75 E-05	5.0	50000	0.08	750
Glass	Glass	65997-17-3	8.75 E-05	5.0	50000	0.08	750
Organic materials	Reaction product: bisphenol-A-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	1.75 E-06	0.1	1000	0.00	15
Subtotal			1.75 E-03	100.00	1000000	1.50	15001

Package Totals	Weight (g)	Percentage (%)	PPM
	1.17 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Lead Count	3
Terminal Finish	SnPb

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High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound							
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Other inorganic materials	Silica	Proprietary	3.30 E-02	71.7	717000	28.27	282719
Thermosets	Epoxy Resin	Proprietary	6.90 E-03	15.0	150000	5.91	59146
Thermosets	Phenol Resin	Proprietary	2.30 E-03	5.0	50000	1.97	19715
Thermosets	Antimony Trioxide	1309-64-4	1.38 E-03	3.0	30000	1.18	11829
Others	Additives	Proprietary	1.38 E-03	3.0	30000	1.18	11829
Thermosets	Brominated Epoxy	Proprietary	9.20 E-04	2.0	20000	0.79	7886
Other inorganic materials	Carbon Black	1333-86-4	1.38 E-04	0.3	3000	0.12	1183
Subtotal			4.60 E-02	100.0	1000000	39	394308
Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Copper & its alloys	Tin	7440-31-5	6.43 E-05	0.1	1002	0.06	551
Subtotal			6.42 E-02	100	1000000	55	550072
Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.29 E-04	100	1000000	0.11	1102
External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.35 E-03	85	850000	1.16	11585
Tin & its alloys	Lead	7439-92-1	2.39 E-04	15	150000	0.20	2044
Subtotal			1.59 E-03	100	1000000	1.36	13629
Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.19	1886
Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.80 E-03	100	1000000	2.40	24001
Die Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	6.13 E-04	35.00	350000	0.53	5250
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-2	6.13 E-04	35.00	350000	0.53	5250
Thermoset	Epoxy Resin	Proprietary	4.38 E-04	25.00	250000	0.38	3750
Others	Amine	Proprietary	8.75 E-05	5.0	50000	0.08	750
Subtotal			1.75 E-03	100.00	1000000	1.50	15001
Package Totals			Weight (g)	Percentage (%)		PPM	
			1.17 E-01	100.00		1000000	

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